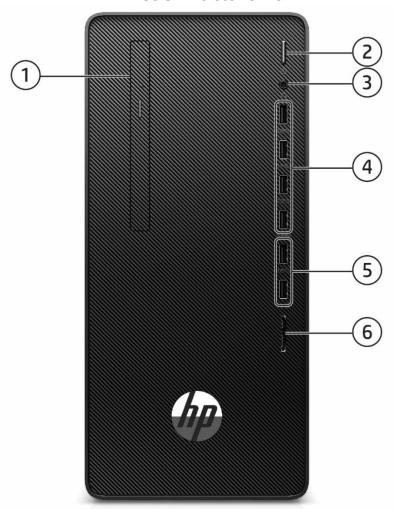
Overview

HP 290 G4 Microtower PC



Front

- 1. Slim-height Bay supporting an optical disk drive (Optional)
- 2. Power Button
- 3. Combo jack, Headphone/ Microphone
- 4. (4) SuperSpeed USB 5Gbps port²
- 5. (2) SuperSpeed USB 10Gbps port²
- 6. SD Card Reader (Optional)

Not Shown

Slots (1) PCI Express x16

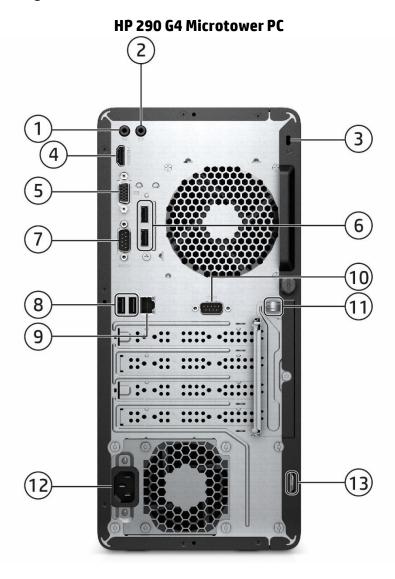
- (1) PCI Express x1
- (1) PCI¹
- (1) M.2 for WLAN
- (1) M.2 2242/2280 storage

Bays (1) 3.5" or 2.5" internal HDD bay

- (1) 3.5" or 2.5" internal HDD bay (share bay with caddy)
- (1) 9.5mm internal optical drive bay
- 1. Available on select skus only.
- 2. SuperSpeed USB 10Gbps = USB 3.2 Gen2. SuperSpeed USB 5Gbps = USB 3.2 Gen1



Standard Features and Configurable Modules



Back

- 1. Audio Line out
- 2. Audio Line in
- 3. Standard lock slot
- 4. HDMI Port1
- 5. VGA Port1
- Connector (2) USB 2.0 port (Optional)³

Not Shown

- (1) PS/2 Port (Optional)
- (1) Parallel Port (Optional via PCIex1 slot),
- (1) 4 Serial Port (Optional via PCIex1 slot)²
- (1) Internal Speaker (Optional)
- (1) Intrusion Sensor (Optional)

- 7. Serial Port
- 8. Connector (2) USB 2.0 port
- 9. RJ-45 Network
- 10. Serial Port (Optional)
- 11. Integrated accessories cable lock
- 12. Power Cord Connector³
- 13. Padlock Loop

- 1. Port will be covered up when configured with processor which is without internal graphics.
- 2. Available in select countries only.
- 3. Power cord connector will be in different position, depends on which power supply configured.

Standard Features and Configurable Modules

AT A GLANCE

- Windows 10 Pro, Windows 10 Home or FreeDOS
- Intel® H470 chipset supporting Intel® 10th processors featuring Intel® UHD Graphics
- Supports an optional discrete graphics card
- Integrated 10/100/1000 Ethernet Controller or 802.11ac (1x1) Wi-Fi® and Bluetooth® 4.2 Combo
- Up to 64GB DDR4- 2933 Unbuffered Memory (UDIMM)
- Independent monitor support via VGA and HDMI interfaces
- TPM 2.0 support (either dTPM or fTPM) 1
- Supports both Hard Disk Drives and M.2 PCIe NVMe Solid State Drives
- Up to 10 USB Ports (including native 4 SuperSpeed USB 5Gbps ports and 2 SuperSpeed USB 10Gbps³ and 2 USB 2.0 ports)
- 180W/310W 90% HE power supply
- Security cable lock supported (sold separately)
- Intrusion sensor supported (Optional)
- Optional HP Care Services available; terms and conditions vary by country; certain restrictions and exclusions apply²
- 1. TPM feature will be supported on machine pre-configured with FreeDOS, and will be default set as enabled in BIOS setup menu if the machine is dTPM, but will be default set as disabled in BIOS setup menu if the machine is fTPM.
- 2. HP Care Services are optional. Service levels and response times for HP Care Services may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.
- 3. SuperSpeed USB 10Gbps = USB 3.2 Gen2. SuperSpeed USB 5Gbps = USB 3.2 Gen1

NOTE: See important legal disclosures for all listed specs in their respective features sections.



Standard Features and Configurable Modules

PRODUCT NAME

HP 290 G4 Microtower PC

OPERATING SYSTEM

Preinstalled Windows 11 Pro¹

Windows 11 Home - HP recommends Windows 11 Pro for business¹

Windows 10 Pro

Windows 10 Home - HP recommends Windows 11 Pro for business^{1,2}

Pre-installed (other) FreeDOS

1. Device comes with Windows 10 and a free Windows 11 upgrade or may be preloaded with Windows 11. Upgrade timing may vary by device. Features and app availability may vary by region. Certain features require specific hardware (see Windows 11 Specifications).

2. Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows is automatically updated and enabled. High speed interneet and Microsoft account required. ISP fees apply and additional requirements may apply over time for updates. See http://www.windows.com.

PROCESSORS

Intel® Celeron® Processors^{2,3}

CPU Intel Celeron G5900 Dual Core 3.4GHz 2666MHz 58W (3.4GHz, 2MB cache, 2 cores) CPU Intel Celeron G5905 Dual Core 3.4GHz 2666MHz 58W (3.4GHz, 2MB cache, 2 cores)

Intel® Pentium® Processors^{2,3}

CPU Intel Pentium Gold G6400 Dual Core 4.0GHz 2666MHz 58W (4.0GHz, 4MB cache, 2 cores)

CPU Intel Pentium Gold G6405 Dual Core 4.1GHz 2666MHz 58W (4.1GHz, 4MB cache, 2 cores)

CPU Intel Pentium Gold G6600 Dual Core 4.2GHz 2666MHz 58W (4.2GHz, 4MB cache, 2 cores)

CPU Intel Pentium Gold G6605 Dual Core 4.3GHz 2666MHz 65W (4.3GHz. 4MB cache. 2 cores)

Intel 10th Processors

Intel® Core™ i3^{2,3}

CPU Intel Core i3-10100 4C 3.6GHz 2666MHz 65W (3.6GHz, turbo up to 4.1GHz, 6MB cache, 4 cores) CPU Intel Core i3-10105 4C 3.7GHz 2666MHz 65W (3.7GHz, turbo up to 4.4GHz, 6MB cache, 4 cores)

Intel® Core™ i5^{2,3}

CPU Intel Core i5-10400 6C 2.9GHz 2666MHz 65W (2.9GHz, turbo up to 4.3GHz, 12MB cache, 6 cores) CPU Intel Core i5-10500 6C 3.1GHz 2666MHz 65W (3.1GHz, turbo up to 4.5GHz, 12MB cache, 6 cores)

Intel® Core™ i7^{2,3}

CPU Intel Core i7-10700 8C 2.9GHz 2933MHz 65W (2.9GHz, Up to 4.8GHz with Intel® Turbo Boost4, 16MB cache, 8 cores)

2.Your product does not support Windows 8 or Windows 7, In accordance with Microsoft's support policy, HP does not support the Windows® 8 or Windows 7 operating system on products configured with Intel 8th or 9th generation and forward processors or provide any Windows® 8 or Windows 7 drivers on http://www.support.hp.com

3. Multi-Core is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. 64-bit computing system required. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.
4. Intel® Turbo Boost technology requires a PC with a processor with Intel Turbo Boost capability. Intel Turbo Boost performance varies depending on hardware, software and overall system. See http://www.intel.com/technology/turboboost for more information

*NOTE: Only available on selected region



Standard Features and Configurable Modules

CHIPSET

Intel® H470 Chipset

GRAPHICS

Integrated5,6

Intel® UHD

Graphics 630 (integrated on 10th Core i processors and Pentium Gold G6600)

Intel® UHD

Graphics 610 (integrated on Pentium Gold G6400 and Celeron)

Discrete Graphics

AMD Radeon™ RX550X 4GB GFX AMD Radeon™ 520 1GB GFX NVIDIA® GeForce® GT730 2GB GFX NVIDIA® GeForce® GTX1660 Super 6GB GFX*

5. HD content required to view HD images.

6. Integrated Intel software is available on select models only and requires separately purchased projector, tv or computer monitor with an integrated or external receiver. External receivers connect to the projector, tv or computer monitor via a standard VGA, HDMI cable, also sold separately.

*NOTE: Available in select countries only

MEMORY7

Form Factor	Туре	Maximum	# of Slots
Microtower	DDR4 2933 (Transfer rates up to 2933 MT/s) DDR4 2666 (Transfer rates up to 2666 MT/s)	64 GB capacity	2 DIMM

4GB DDR4-2933 UDIMM NECC (1x4GB)

8GB DDR4-2933 UDIMM NECC (1x8GB)

8GB DDR4-2933 UDIMM NECC (2x4GB)

16GB DDR4-2933 UDIMM NECC (2x8GB)

16GB DDR4-2933 UDIMM NECC (1x16GB)

64GB DDR4-2933 UDIMM NECC (2x32GB)

4GB DDR4-2666 UDIMM NECC (1x4GB)

8GB DDR4-2666 UDIMM NECC (1x8GB)

8GB DDR4-2666 UDIMM NECC (2x4GB)

16GB DDR4-2666 UDIMM NECC (1x16GB)

16GB DDR4-2666 UDIMM NECC (2x8GB)

64GB DDR4-2666 UDIMM NECC (2x32GB)

7. Memory modules support data transfer rates up to 2933 MT/s; actual data rate is determined by the system's configured processor. See processor specifications for supported memory data rate.

NOTE: DDR4-2933 UDIMM is only available for 10th Gen i7 processor.



Standard Features and Configurable Modules

STORAGE

SATA3 - 3.5" or 2.5" 6Gb/s HDDs

2TB 7200 RPM SATA Hard Disk Drive 1TB 7200 RPM SATA Hard Disk Drive 500GB 7200 RPM SATA Hard Disk Drive

Solid State Drives

128GB M.2 NVMe

256GB M.2 NVMe

512GB M.2 NVMe

SD Card Reader⁸

SD/SDHC/SDXC SD Card Reader

Intel Optane Memory⁸

SSD Intel 16GB 2280 Optane Memory

8. Optional per configuration

OPTICAL DISC DRIVES

DVD-ROM 9.5mm

DVD-Writer⁹ 9.5mm

9. HD-DVD disks cannot be played on this drive. No support for DVD-RAM. Actual speeds may vary. Don't copy copyright-protected materials. Double Layer discs can store more data than single layer discs. Discs burned with this drive may not be compatible with many existing single-layer DVD drives and players.

NETWORKING¹⁰

Ethernet (RJ-45)

Integrated 10/100/1000M GbE LAN

Wi-Fi® and Bluetooth®

802.11ac (1x1) Wi-Fi® and Bluetooth® 4.2 Combo

10. Wireless cards are optional or add-on features and requires separately purchased wireless access point and internet service. Availability of public wireless access points limited.



Standard Features and Configurable Modules

AUDIO / MULTIMEDIA

Realtek ALC3601 / ALC3867-CG Integrated Hi-Definition Audio Combo Jack, Headphone / Microphone Line-in / Line-out (3.5mm)

KEYBOARDS AND POINTING DEVICES¹¹

Keyboard

USB Business Slim Wired Keyboard HP USB Wired Keyboard Business Slim USB Antimicrobial Wired Keyboard (China) Business Slim PS/2 Wired Keyboard (for machine configured with PS/2 port) No KB Option

Mouse

Antimicrobial USB Mouse (China)
HP Optical USB Mouse
Universal Wired USB Mouse
USB Hardened Mouse (Specific region)
HP PS/2 Mouse (for machine configured with PS/2 port)
No Mouse Option

11. Keyboards and mouse are optional or add-on features.

PORTS

Front

Slim-height Bay - supporting an optical disk drive (Optional)

Power Button

Combo jack, Headphone / Microphone

SD Card Reader (Optional)

- (2) SuperSpeed USB 10Gbps port**
- (4) SuperSpeed USB 5Gbps port**

Not Shown

- (1) PCI Express x16
- (1) PCI Express x1
- (1) Full-height PCI (Available on selected sku)
- (1) M.2 for WLAN
- (1) M.2 2242/2280 storage

Rear

Audio Line out



Standard Features and Configurable Modules

Audio Line in

HDMI Port

VGA Port

Serial Port (Optional on selected sku)

2nd Serial Port (Optional)

Standard Lock Slot

(2) USB 2.0 port

(2) USB 2.0 port (Optional on selected sku)

RJ-45 Network connector

Power cord connector

Padlock loop

Integrated accessories cable lock

Not Shown

- (1) PS/2 Port (Optional)
- (1) Parallel Port (Optional via PCIex1 slot)
- (1) 4x Serial port (Optional via PClex1 slot)*
- (1) Internal Speaker (Optional)
- (1) Intrusion Sensor (Optional)

NOTE*: Available in select countries only.

NOTE**: SuperSpeed USB 10Gbps = USB 3.2 Gen2. SuperSpeed USB 5Gbps = USB 3.2 Gen1

BAYS

- (1) 9.5mm external slimline ODD bay (Optional)
- (1) 3.5" or 2.5" internal HDD or bay
- (1) 3.5 or 2.5" internal HDD bay (share bay with caddy)



Standard Features and Configurable Modules

SOFTWARE COMPONENTS AND APPLICATIONS WITH WINDOWS

Security and Protection

McAfee* LiveSafe™ 12

Productivity

Buy Office (sold separately)
Dropbox¹³
Xerox® DocuShare® (90 days free trial offer)¹⁶

ODD Playback

sMedio True DVD for HP

Movies

Netflix14

App Stores and Content Purchasing

Amazon¹⁴

HP Utilities and Support

HP Documentation HP JumpStarts HP Audio Switch¹⁵ HP Support Assistant

BTB

HP Setup Integrated 00BE

Hardware Enabling Drivers or software utility

HP System Event Utility

- 12. Free 1-year subscription of McAfee LiveSafe service included. Internet access required and not included. Subscription required after expiration 13. New Dropbox users are eligible to get 25 GB of Dropbox space free for 12 months from date of registration. For complete details and terms of use, including cancellation policies, visit the Dropbox website at https://www.dropbox.com/help/space/hp-promotion. Internet service required and not included.
- 14. Internet access required and not included.
- 15. Easily switch between speaker and microphone sources with intuitive controls and a consistent app experience.
- 16. Simply sign up and start using Xerox® DocuShare® Go. No credit card. No obligation. Data will become unavailable unless a subscription is entered before the end of the 90 days free trial period. See visit https://http://www.xerox.com/docusharego for details.
- *NOTE: Available in Latin America countries only.

POWER SUPPLY¹⁷

180 W

ENERGY® STAR® Libra2 EPA90 (Gold) Full range 115V/230V

310 W

SFF ENTL EPA90 (Gold) Full range 115V/230V

500 W

EPA90 (Gold) Full range 115V/230V

17. All power supplies are not available in every region.



Standard Features and Configurable Modules

DIMENSIONS AND WEIGHT

Dimensions

6.12 x 11.93 x 13.28 in (155 x 303 x 337 mm)

Weight

10.4 lbs / 4.7 kg

UNIT ENVIRONMENT AND OPERATING CONDITIONS

General Unit Operating Guidelines

- Keep the computer away from excessive moisture, direct moisture and the extremes of heat and cold, to ensure that unit is operated within the specified operating range.
- Leave a 10.2 cm (4 in) clearance on all vented sides of the computer to permit the required airflow.
- Never restrict airflow into the computer by blocking any vents or air intakes.
- Do not stack computers on top of each other or place computers so near each other that they are subject to each other's re-circulated or preheated air.
- Occasionally clean the air vents on the front, back, and any other vented side of the computer. Lint, dust and other foreign
 matter can block the vents and limit the airflow.
- If the computer is to be operated within a separate enclosure, intake and exhaust ventilation must be provided on the
 enclosure, and the same operating guidelines listed above will still apply.

Temperature Range Operating: 5° to 35° C¹⁸

Non-operating: -30° to 60° C18

Relative Humidity Operating: 5% to 90% (non-condensing at ambient)

Non-operating: 5% to 90% (non-condensing at ambient)

Maximum Altitude (unpressurized) Operating: 5000 m

Non-operating: 50000ft (15240 m)

18. Operating temperature is de-rated 1.0 deg C per 300 m (1000 ft) to 3000 m (10,000 ft) above sea level, no direct sustained sunlight. Maximum rate of change is 10 deg C/Hr. The upper limit may be limited by the type and number of options installed.

Eco-Label Certifications	This product has received or is in the process of being certified to the following approvals and may be		
& declarations	labeled with one or more of these marks:		
	IT ECO declaration		
	US ENERGY STAR®		
	US Federal Energy Management Program (FEMP)		
	 EPEAT[®] Gold registered in the United States. See http://www.epeat.net for registration 		
	status in your country.		
	TCO Certified		
	China Energy Conservation Program (CECP)		
	China State Environmental Protection Administration (SEPA)		
	Taiwan Green Mark		
	Korea Eco-label		
	Japan PC Green label		
	Commission Regulation (EC) No 617/2013 (ErP Lot 3)		
System Configuration	The configuration used for the Energy Consumption and Declared Noise Emissions data for the		
	Desktop model is based on a "Typically Configured Desktop".		

Standard Features and Configurable Modules

Energy Consumption (in accordance with US ENERGY STAR® test method)	115VAC, 60Hz	230VAC	, 50Hz	100VAC, 50Hz
Normal Operation (Short idle)	35.98W	36.7	6W	36.52W
Normal Operation (Long idle)	33.27W	33.0	3W	33.26W
Sleep	1.08W	1.1		1.27W
Off	0.27W	0.3	W	0.26W
	NOTE: Energy efficiency data listed is family. HP computers marked with the Environmental Protection Agency (EP offer ENERGY STAR® compliant config featuring a hard disk drive, a high efficiency	e ENERGY STAR® Log A) ENERGY STAR® spe urations, then energ ciency power supply,	o are compliant with ecifications for com y efficiency data list and a Microsoft Wir	n the applicable U.S. puters. If a model family does not ted is for a typically configured PC ndows® operating system.
Heat Dissipation*	115VAC, 60Hz	230VAC	, 50Hz	100VAC, 50Hz
Normal Operation (Short idle)	122.69 BTU/hr	125.35 E	3TU/hr	124.53 BTU/hr
Normal Operation (Long idle)	113.45 BTU/hr	112.63 E		113.42 BTU/hr
Sleep	3.68 BTU/hr	3.75 B1		4.33 BTU/hr
Off	0.92 BTU/hr	1.02 B1	ΓU/hr	0.89 BTU/hr
Declared Noise Emissions	NOTE: Heat dissipation is calculated b hour.	ased on the measure		the service level is attained for one Sound Pressure
(in accordance with ISO 7779 and ISO 9296)	Sound Power (L _{WAd} , bels)			(L _{pAm} , decibels)
Typically Configured – Idle	3.7			24.7
Fixed Disk – Random writes	4			29.8
Longevity and Upgrading	This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the product may include: Spare parts are available throughout the warranty period and or for up to "3" years after the end of production.			
Batteries	This battery(s) in this product comply with EU Directive 2006/66/EC			
	Batteries used in the product do not contain: Mercury greater the1ppm by weight Cadmium greater than 20ppm by weight			
	Battery size: CR2032 (coin cell) Battery type: Lithium			
Additional Information	 This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC. This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive – 2002/96/EC. This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986). This product is in compliance with the IEEE 1680.1 (EPEAT) standard at the <silver> level, see http://www.epeat.net.</silver> Plastics parts weighing over 25 grams used in the product are marked per IS011469 and IS01043. 			



Standard Features and Configurable Modules

	This product contains 28.2% post-consumer recycled plastic (by wt.)		
	• This product is 91.7% recycle-able when properly disposed of at end of life.		
Packaging Materials	External:	PAPER/Paperboard	1220 g
	Internal:	PAPER/Molded Pulp	520 g
		PLASTIC/Polyethylene low density - LDPE	53 g
Material Usage	This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf): - Asbestos - Certain Azo Colorants - Certain Brominated Flame Retardants – may not be used as flame retardants in plastics - Cadmium - Chlorinated Hydrocarbons - Chlorinated Paraffins - Formaldehyde - Halogenated Diphenyl Methanes - Lead carbonates and sulfates - Lead and Lead compounds - Mercuric Oxide Batteries - Nickel – finishes must not be used on the external surface designed to be frequently handled or carried by the user Ozone Depleting Substances - Polybrominated Biphenyls (PBBs) - Polybrominated Biphenyl Ethers (PBBEs) - Polybrominated Biphenyl (PCB) - Polychlorinated Terphenyls (PCT) - Polychlorinated Terphenyls (PCT) - Polycyinyl Chloride (PVC) – except for wires and cables, and certain retail packaging has been voluntarily removed from most applications Radioactive Substances		
Packaging Usage	 Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO) HP follows these guidelines to decrease the environmental impact of product packaging: Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials. Eliminate the use of ozone-depleting substances (ODS) in packaging materials. Design packaging materials for ease of disassembly. Maximize the use of post-consumer recycled content materials in packaging materials. Use readily recyclable packaging materials such as paper and corrugated materials. Reduce size and weight of packages to improve transportation fuel efficiency. Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards. 		npact of product packaging: mercury and cadmium in packaging ackaging materials. ials in packaging materials. id corrugated materials. ion fuel efficiency. 469 and DIN 6120 standards.
End-of-life Management and Recycling	HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner. The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment. Global Citizenship Report http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html Eco-label certifications http://www8.hp.com/us/en/hp-information/environment/ecolabels.html		

Standard Features and Configurable Modules

	ISO 14001 certificates: http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/PC_GBU_Product_Design_ISO_14K_ Certificate.pdf and http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf
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SERVICE AND SUPPORT

On-site Warranty 1: Available three-year (3-3-3) or one-year (1-1-1) limited warranty (varies by country) delivers on-site, next business day 2 service for parts and labor and complimentary limited technical support.3 Three-year onsite and labor are not available in all countries. Service offers terms up to 5 years by choosing an optional HP Care Pack.4 To choose the right level of service for your HP product, visit HP Care Pack Central: http://www.hp.com/go/cpc.

NOTE 1: Terms and conditions may vary by country. Certain restrictions and exclusions apply. Other warranty variations may be offered in your region.

NOTE 2: On-site service may be provided pursuant to a service contract between HP and an authorized HP third-party provider, and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country. **NOTE 3:** Technical support applies only to HP-configured and third-party HP qualified hardware and software.

NOTE 4: Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit http://www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.



Technical Specifications - Graphics

GRAPHICS

<u>-</u>	itegrated on Core i7/i5/i3/Pentium G6500 and above processors) Itegrated on Pentium G6400 and below/ and Celeron)
DisplayPort™	Multimode capable; supports HDCP, DisplayPort™ Audio (2 streams), HBR2 link rates and Multi-Stream Technology for a maximum of 3 displays (including the integrated panel)
Memory	Additional memory is allocated for graphics as needed using Intel's Dynamic Video Memory Technology (DVMT), to provide an optimal balance between graphics and system memory use.
Maximum Graphics Memory	Windows 10: >4 GB
Maximum Color Depth	32 bits/pixel
Graphics/Video API Support	10 th Generation Intel® Core Processors, Pentium and Celeron With Intel® UHD Graphics 630 Pentium® and Celeron® With Intel® UHD Graphics 610
Supported Display Resolutions and Refresh Rates	Max. Resolution (VGA) 2048 x 1536@60Hz Max. Resolution (HDMI) 4096 x 2160@60Hz

Note: The actual amount of maximum graphics memory can be less than the amounts listed above depending upon your computer's configuration.

Note: other resolutions may be available but are not recommended as they may not have been tested and qualified by HP Only supported on displays connected to the external DisplayPort™ connector.



Technical Specifications - Graphics

AMD Radeon™ R7 430 2GB Graphics Card

Engine Clock780 MHzMemory Clock1100 MHzMemory Size(width)2GB(64-bit)Memory Type256M x 32 GDDR5

Max. Resolution(VGA) 2048x1536

Max. Resolution(DP) 4096x2160@60Hz

Multi Display Support 2 displays

HDCP Compliance yes **Rear I/O connectors(bracket)** VGA+DP

Cooling(active/passive) Active fan-sink (Active cooling with dynamic speed)

Total power consumption(W) <50W

PCB form-factor with bracket LP PCB with FH/LP bracket

AMD® Radeon™ RX550X 4 GB FH PCIe x16

Engine Clock 1183MHz
Memory Clock 6 Gbps
Memory Size(width) 4 GB(128-bit)

Memory Type GDDR5

 Max. Resolution(HDMI)
 4096x2160 @ 60Hz

 Max. Resolution(DP)
 5120x2880 @ 60Hz

Multi Display Support2 displaysHDCP ComplianceYes

Rear I/O connectors(bracket) HDMI, DPx2

Cooling(active/passive) Active fan-sink (Active cooling with dynamic speed)

Total power consumption(W) <50W

PCB form-factor with bracket LP (low profile) PCB with FH/LP bracket

AMD Radeon™ 520 1GB Graphics Card

Engine Clock780 MHzMemory Clock1100 MHzMemory Size(width)1GB(32-bit)

Memory Type 256M x 32 GDDR5

Max. Resolution(VGA) 2048x1536

Max. Resolution(DP) 4096x2160@60Hz

Multi Display Support 2 displays
HDCP Compliance yes

Rear I/O connectors(bracket) VGA+DP

Cooling(active/passive) Active fan-sink (Active cooling with dynamic speed)

Total power consumption(W) <50W

PCB form-factor with bracket LP PCB with FH/LP bracket



Technical Specifications - Graphics

NVIDIA® GeForce® GTX 1660 Super 6GB Graphics Card

Engine Clock 1785 MHz
Memory Clock 7000 MHz
Memory Size(width) 6GB(192-bit)

 Memory Type
 256M x 32 GDDR6 @6pcs

 Max. Resolution(DVI)
 7680x4320@120Hz

 Max. Resolution(DP)
 7680x4320@120Hz

Multi Display Support 3 displays

HDCP Compliance yes

Rear I/O connectors(bracket) DVI-D+DP+HDMI

Cooling(active/passive) Active fan-sink(Active cooling with dynamic speed)

Total power consumption(W) <125W

PCB form-factor with bracket FH PCB with FH bracket



Technical Specifications - Storage

STORAGE*

HP 2 TB 7.2K rpm SATA 6.0Gb/s 3.5" Hard Disk Drive

Capacity 2 TB

Rotational Speed 7,200 rpm **Interface** SATA 6Gb/s NCQ

Buffer Size 64 MB

 Logical Blocks
 3,907,029,168

 Seek Time
 Read: <8.5 ms</td>

 Write: <9.5 ms</th>

 Height
 1.028 in/26.11 mm

 Width
 4.0 in/101.6 mm

Operating Temperature 32° to 140° F (0° to 60° C)

1 TB 7.2K rpm SATA 6.0Gb/s 3.5" Hard Disk Drive

Capacity 1 TB

Rotational Speed 7,200 rpm

Interface Serial ATA 3.0 (6.0 Gb/s)

Buffer Size 32 MB

Logical Blocks 1,953,525,168

Seek Time Single Track: 2.0 ms

Average: 11 ms Full-Stroke: 21 ms

Height 1 in/2.54 cm

Width Media diameter: 3.5 in/8.89 cm

Physical size: 4 in/10.2 cm

Operating Temperature 41° to 131° F (5° to 55° C)

500 GB 7.2K rpm SATA 6.0Gb/s 3.5" Hard Disk Drive

Capacity 500 GB
Rotational Speed 7,200 rpm

Interface Serial ATA 3.0 (6.0 Gb/s)

Buffer Size 32 MB

Logical Blocks 1,953,525,168

Seek Time Single Track: 2.0 ms
Average: 11 ms

Full-Stroke: 21 ms

Height 1 in/2.54 cm

Width Media diameter: 3.5 in/8.89 cm

Physical size: 4 in/10.2 cm

Operating Temperature 41° to 131° F (5° to 55° C)



Technical Specifications - Storage

128 GB M.2 2280 PCIe NVMe Three Layer Cell SSD

Drive Weight < 10a Capacity 128GB Height 2.38mm Length 80mm Width 22mm Interface PCIE Gen3x4 Up to 2800MB/s **Maximum Sequential Read Maximum Sequential Write** Up to 600MB/s **Logical Blocks** 250,069,680

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features APST; ASPM L1.2; NVME spec 1.2

256 GB M.2 2280 PCIe NVMe Three Layer Cell SSD

Drive Weight < 10g Capacity 256GB Height 2.38mm 80mm Length Width 22mm Interface PCIE Gen3x4 **Maximum Sequential Read** Up to 2700MB/s **Maximum Sequential Write** Up to 1000MB/s **Logical Blocks** 500,118,192

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features APST; ASPM L1.2; NVME spec 1.2

512 GB M.2 2280 PCIe NVMe Three Layer Cell SSD

Drive Weight < 10a 512GB Capacity Height 2.38mm 80mm Length Width 22mm Interface PCIE Gen3x4 **Maximum Sequential Read** Up to 2900MB/s **Maximum Sequential Write** Up to 1100MB/s **Logical Blocks** 1,000,215,216



Technical Specifications - Storage

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features APST; ASPM L1.2; NVME spec 1.2

256 GB M.2 2280 PCIe NVMe SSD

Drive Weight< 10g</td>Capacity256 GBHeight2.38mmLength80mmWidth22mmInterfacePCIE Gen3

Maximum Sequential ReadUp to 1600MB/sMaximum Sequential WriteUp to 780MB/sLogical Blocks500,118,192

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features APST; ASPM L1.2; NVME spec 1.2

512 GB M.2 2280 PCIe NVMe SSD

Drive Weight< 10g</th>Capacity512 GBHeight2.38mmLength80mmWidth22mmInterfacePCIE Gen3

Maximum Sequential ReadUp to 1600MB/sMaximum Sequential WriteUp to 860MB/sLogical Blocks1,000,215,216

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features APST; ASPM L1.2; NVME spec 1.2

500 GB 7200RPM 2.5in SATA HDD

Capacity500 GBRotational Speed7,200 rpmInterfaceSATA 6 Gb/sBuffer Size32 MB

Logical Blocks 976,773,168
Seek Time 12 ms (Average)

Height0.267 in/6.8 mm (nominal)Width (nominal)2.75 in/70 mm (nominal)



Technical Specifications - Storage

Operating Temperature 41° to 131° F (5° to 55° C)

1TB 7200RPM 2.5in SATA HDD

Capacity 1 TB

Rotational Speed7,200 rpmInterfaceSATA 6 Gb/sBuffer Size32 MB

Logical Blocks 1,953,525,168
Seek Time 12 ms (Average)

Height0.374 in/9.5 mm (nominal)Width (nominal)2.75 in/70 mm (nominal)Operating Temperature41° to 131° F (5° to 55° C)



Technical Specifications – Optical Drives

OPTICAL DISC DRIVES

HP 9.5mm Desktop G2 Slim DVD Writer Drive

Height 9.5 mm height

Orientation Either horizontal or vertical

Interface type SATA/ATAPI

Disc recording capacity Up to 8.5 GB DL or 4.7 GB standard

Dimensions (W x H x D) 5.04 x 0.37 x 5.0 in (128 x 9.5 x 127 mm) without bezel

Weight (max) 0.31 lb (140 g)

Read Speeds DVD-R DL Up to 6X

DVD+R Up to 8X DVD+RW Up to 8X DVD+R DL Up to 6X DVD-R Up to 8X **DVD-RW** Up to 6X CD-R Up to 24X Up to 10X CD-RW DVD-RW, DVD+RW Up to 8X DVD-R DL, DVD+R DL Up to 8X DVD+R, DVD-R Up to 8X DVD-ROM DL, DVD-ROM Up to 8X CD-ROM, CD-R Up to 24X CD-RW Up to 24X

Access time

(typical reads, including

settling)

Full Stroke DVD-ROM: 320 ms (typical), CD-ROM: 320 ms (typical) Stop Time 6 seconds (typical)

Power Source Slimline SATA DC power receptacle

DC Power Requirement 5 VDC ± 5%-100 mV ripple p-p DC Current 5 VDC (< 1000 mA typical, 1600 mA maximum)

Random DVD-ROM: 170 ms (typical), CD-ROM: 170 ms (typical)

Environmental conditions

(operating - non-condensing)

Temperature 41° to 122° F (5° to 50° C)

Relative Humidity 10% to 80%

Maximum Wet Bulb Temperature 84° F (29° C)

HP 9.5mm Desktop G2 Slim DVD-ROM Drive

Height 9.5 mm height

Orientation Either horizontal or vertical

Interface type SATA/ATAPI

Disc recording capacity Up to 8.5 GB DL or 4.7 GB standard

Dimensions (W x H x D) 5.04 x 0.37 x 5.0 in (128 x 9.5 x 127 mm) without bezel

Weight (max) 0.31 lb (140 g)

Read Speeds DVD-R DL Up to 6X

 DVD+R
 Up to 8X

 DVD+RW
 Up to 8X

 DVD+R DL
 Up to 6X

 DVD-R
 Up to 8X

 DVD-RW
 Up to 6X

 CD-R
 Up to 24X



Technical Specifications – Optical Drives

Access time

(typical reads, including

settling)

Random DVD-ROM: 170 ms (typical), CD-ROM: 170 ms (typical) Full Stroke DVD-ROM: 320 ms (typical), CD-ROM: 320 ms (typical)

Stop Time 6 seconds (typical)

Power Source Slimline SATA DC power receptacle

DC Power Requirement 5 VDC ± 5%-100 mV ripple p-p DC Current 5 VDC (< 1000 mA typical, 1600 mA maximum)

Environmental conditions (operating - non-condensing)

Temperature 41° to 122° F (5° to 50° C)

Relative Humidity 10% to 80%

Maximum Wet Bulb Temperature 84° F (29° C)



Technical Specifications – Networking

NETWORKING

10/100/1000 NIC	Ethernet Features	10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14) 100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30) 1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 8023 clauses 40) Auto-Negotiation (Automatic Speed Selection) Full Duplex Operation at all Speeds, Half Duplex operation at 10 and 100 Mbit/s
	Power Management	ACPI compliant – multiple power modes Situation-sensitive features reduce power consumption Advanced link down power saving for reducing link down power consumption
	Performance Features	TCP/IP/UDP Checksum Offload (configurable) Protocol Offload (ARP & NS) Large send offload and Giant send offload Receiving Side Scaling Jumbo Frame 9K
	Manageability	Wake-on-LAN from standby and hibernation (Magic Packet and Microsoft Wake-Up Frame); Wake-on-LAN from off (Magic Packet only) PXE 2.1 Remote Boot Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x, clause 30) Comprehensive diagnostic and configuration software suite Virtual Cable Doctor for Ethernet cable status
	Interface	PCIe + SMBus
	NIC Device Driver Name	PCIe GBE Ethernet Family Controller

Realtek 802.11ac (1x1) Wi	-Fi® and Bluetooth®	4.2 Combo *
Wireless LAN Standards ¹	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac 1. Wireless access point and Internet service required and not included. Availability of public wireless access points limited.	
Interoperability	Wi-Fi® certified modules	
Frequency Bands	802.11b/g/n	2.402 – 2.482 GHz NOTE: The FCC has declared products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 & 15.249 or otherwise disable those channels.
	802.11a/n	4.9 – 4.95 GHz (Japan) 5.15 – 5.25 GHz 5.25 – 5.35 GHz 5.47 – 5.725 GHz 5.825 – 5.850 GHz



Technical Specifications – Networking

Data Rates	802.11b: 1, 2, 5.5, 11 Mbps 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz) 802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, and 80MHz)
Modulation	Direct Sequence Spread Spectrum BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM
Security ²	IEEE and 64 / 128 bit WEP encryption for a/b/g mode only AES-CCMP: 128 bit in hardware 802.1x authentication WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. WPA2 certification IEEE 802.11i Cisco Certified Extensions, all versions through CCX4 and CCX Lite WAPI
	2 Check latest software/driver release for updates on supported security features.
Network Architecture Models	Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)
Roaming	IEEE 802.11 compliant roaming between access points
Output Power ³	802.11b: +14dBm minimum 802.11g: +12dBm minimum 802.11a: +12dBm minimum 802.11n HT20(2.4GHz): +12dBm minimum 802.11n HT40(2.4GHz): +12dBm minimum 802.11n HT20(5GHz): +10dBm minimum 802.11n HT40(5GHz): +10dBm minimum 802.11ac VHT80(5GHz): +10dBm minimum 802.11ac VHT80(5GHz): +10dBm minimum
Power Consumption	•Transmit mode2.0 W •Receive mode1.6 W •Idle mode (PSP)180 mW(WLAN Associated) •Idle mode50 mW(WLAN unassociated) •Connected Standby 10mW •Radio disabled8 mW
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode



Technical Specifications – Networking

Receiver Sensitivity ⁴	802.11b, 1Mbps : -93.5dBm maximu	m		
	802.11b, 11Mbps : -84dBm maximum			
	802.11a/g, 6Mbps : -86dBm maximu	m		
	802.11a/g, 54Mbps : -72dBm maximum 802.11n, MCS07 : -67dBm maximum 802.11n, MCS15 : -64dBm maximum			
	802.11ac, MCS0 : -84dBm maximum			
	802.11ac, MCS9 : -59dBm maximum			
	4 Receiver sensitivity is measured at a p error rate of 10% for 802.11a/g (0FDM r	acket error rate of 8% for 802.11b (CKK modulation) and a packet		
	-			
Antenna type		diversity, mounted in the display enclosure antennas are provided to the card to support WLAN MIMO munications		
Form Factors	PCI-Express M.2 MiniCard			
Dimensions	Type 2230 : 2.3 x 22.0 x 30.0 mm	Type 2230 : 2.3 x 22.0 x 30.0 mm		
Weight	Type 2230 : 2.8g			
Operating Voltage	3.3v +/- 9%			
Temperature	Operating: Non-operating:	14° to 158° F (-10° to 70° C) -40° to 176° F (-40° to 80° C)		
Humidity	Operating: Non-operating:	10% to 90% (non-condensing) 5% to 95% (non-condensing)		
Altitude	Operating: Non-operating:	0 to 10,000 ft (3,048 m) 0 to 50,000 ft (15,240 m)		
LED Activity	LED Amber – Radio OFF; LED White –	Radio ON		
HP Integrated Module with Blue	tooth 4.0/4.1/4.2 Wireless Technolog	у		
Bluetooth® Specification	4.0/4.1/4.2 Compliant			
Frequency Band	2402 to 2480 MHz	2402 to 2480 MHz		
Number of Available Channels	Legacy : 0~79 (1 MHz/CH) BLE : 0~39 (2 MHz/CH)			
Data Rates and Throughput	Legacy : 3 Mbps data rate; throughput up to 2.17 Mbps			
	BLE : 1 Mbps data rate; throughput up to 0.2 Mbps Legacy : Synchronous Connection Oriented links up to 3, 64 kbps, voice channels			
	Legacy : Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)			
Transmit Power	The Bluetooth® component shall operate as a Class II Bluetooth® device with a maximum transmit power of + 4 dBm for BR and EDR.			



Technical Specifications – Networking

Receiver Sensitivity Legacy	
Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW
Range	Legacy : 0~79 (1 MHz/CH) BLE : 0~39 (2 MHz/CH)
Electrical Interface	USB 2.0 compliant
Bluetooth® Software Supported Link Topology	Microsoft Windows Bluetooth® Software
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark
Certifications Bluetooth® Profiles Supported	FCC (47 CFR) Part 15C, Section 15.247 & 15.249
Power Management Certifications	Microsoft Windows ACPI, and USB Bus Support
Certifications Bluetooth® Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 – Link Layer Privacy LE Privacy 1.2 – Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)



Technical Specifications - Audio

HIGH DEFINITION AUDIO

Type Integrated

HD Stereo Codec Realtek ALC3601 / ALC3867

Audio I/O Ports Front side Combo jack for supporting CTIA, Rear side Line-in/ Line-out/ Mic-in jacks

Internal Speaker Amplifier 2W class D mono amplifier for the internal speaker only. External speakers must be powered

externally.

Multi-streaming Capable Playback multi-streaming can be enabled in the audio control panel to allow independent audio

streams to be sent to/from the front and rear jacks or integrated speaker.

HD Audio Codec Realtek ALC3601

Sampling Independent sampling rates for DAC's and ADC's; supports resolutions from 16 to 24-bit; 44.1K/

48 K/96K / 192K Hz for DAC and 44.1K/ 48K/ 96K/ 192K Hz Hz for ADC

Wavetable Syntheses Yes
Analog Audio Yes
of Channels on Line-Out Stereo
Internal Speaker Yes

External Speaker Jack 2W class D mono amplifier for the internal speaker only. External speakers must be powered

externally.

NOTE*: Optional

Technical Specifications - Power

POWER SUPPLY

Operating Voltage Range 90 - 264 VAC Rated Voltage Range 100-240V AC **Rated Line Frequency** 50/60 HZ **Operating Line Frequency** 47 – 63 Hz **Rated Input Current** 180W: <2.3A;

310W: <4A 500W: <6A 180W active PFC

Rated Input Current with Energy Efficient* Power

Supply

87/90/87% efficient at 20/50/100% load (115V) 88/92/88% efficient at 20/50/100% load (230V);

310W active PFC

87/90/87% efficient at 20/50/100% load (115V) 88/92/88% efficient at 20/50/100% load (230V)

500W active PFC

87/90/87% efficient at 20/50/100% load (115V) 88/92/88% efficient at 20/50/100% load (230V)

+12.1V DC Output

Current Leakage (NFPA 99:

2102)

Less than 500 microamps of leakage current at 120 Vac with the ground wire disconnected, as required for Non-patient Electrical Appliances and Equipment used in a patient care facility or

that contact patients in normal use. Per section 10.3.5.1.

Less than 100 microamps of leakage current at 120 Vac with the ground wire intact with normal polarity, as required for Non-patient Electrical Appliances and Equipment used in a patient care

facility or that contact patients in normal use. Per section 10.3.5.1.

180W/310W: 70*25mm (linear type) **Power Supply Fan**

500W: 70*25mm (PWM type)

Technical Specifications – Weights and Dimensions

WEIGHT AND DIMENSIONS

Chassis (W x D x H) 6.12 x 11.93 x 13.28 in (155 x 303 x 337 mm) (w/ bezel)

System Volume 15.1 L

System Weight* 10.4 lbs / 4.7 kg

 Packaged
 11.3 x 15.75 x 19.65 in

 (H x W x D)
 287 x 400 x 499 mm

Shipping Weight 17.64lb / 8 kg

Palletization 6 units per layer

Profile 7layer max
42 per pallet

Footprint

-85.31x39.37x47.24 in (2167 x 1000 x1200 mm)



After-Market Options (availability may vary by region)

AFTERMARKET OPTIONS

Туре	Description	Part #
Memory	HP 4GB DDR4-2666 DIMM	3TK85AA
	HP 8GB DDR4-2666 DIMM	3TK87AA
	HP 16GB DDR4-2666 DIMM	3TK83AA
Storage	HP 500GB SATA 6.0Gb/s Hard Drive	QK554AA
	HP 1TB 7200rpm SATA 6Gbps Hard Drive	QK555AA
	HP PCIe NVME TLC 256GB SSD M.2 Drive	1CA51AA
	HP 256GB SATA TLC Non-SED Solid State Drive	P1N68AA
	HP 9.5mm G3 8/6/4 SFF G4 400 SFF/MT DVD Writer	1CA53AA
Graphics	NVIDIA® GT 730 2GB DP Card	Z9H51AA
Grupines -	AMD Radeon™ R7 430 2GB 2DP Card	5JW82AA
Security	HP Business PC Security Lock V3 Kit	3XJ17AA
Security	HP Keyed Cable Lock 10mm kit	T1A62AA
Adapters	HP HDMI Standard Cable Kit	T6F94AA
Auapters	HP USB to Serial Port Adapter	J7B60AA
	HP PCIe x1 Parallel Port Card	N1M40AA
Networking	Intel Ethernet I210-T1 GbE NIC Card	E0X95AA
Input	HP USB Mouse	QY777AA
	HP USB Hardened Mouse	P1N77AA
	HP USB Grey v2 Mouse	Z9H74AA
	HP USB Keyboard	QY776AA
	HP PS/2 Business Slim Keyboard	N3R86AA
	HP USB Business Slim Keyboard	N3R87AA
	HP Backlit USB Mechanical Keyboard	4RV35AA
	HP USB Antimicrobial Slim Keyboard and Mouse	Z9H50AA
Others	HP Business Headset v2	T4E61AA
	HP S101 Speaker bar	5UU40AA



Change Log

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Date of change:	Version History:	Change	Description of change:
June 4, 2020	From v1 to v2	Remove	Nvidia GeForce GT730 2GB Card from Graphics section
June 5, 2020	From V2 to V3	Added	Disclaimer #4 in rear call outs section
July 21, 2020	From V3 to V4	Added	Environmental section
July 24, 2020	From V4 to V5	Added	Intel Celeron G5905
July 29, 2020	From V5 to V6	Correction	Dimensions order
September 24, 2020	From V6 to V7	Addition	Xerox® DocuShare® and footnote to software section.
November 2, 2020	From V7 to V8	Addition	Disclaimer an update to 🛘 17-10700 information in processors section
March 3, 2021	From V8 to V9	Update	Environmental specs updated
June 23, 2021	From V9 to V10	Addition	ALC3867-CG added to Audio specs
August 31, 2021	From V10 to V11	Removal	Footnote from rearview call outs image
September 23, 2021	From V11 to V12	Update	EPEAT disclaimer
October 18, 2021	From v12 to v13	Addition	G6405, G6605 and Core i3-10105 processors added
October 29, 2021	From v13 to v14	Update	OS section
June 15, 2022	From v14 to v15	Update	Intel® Core™ i5 processors / Environmental table certifications updated

